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REMARKS

In the Office Action, claims 1-3, 7, 11-13, 15-17, 21 and 25-26 are rejected under 35 U.S.C. §102(c) as being anticipated by Sota et al., claims 4, 6, 8, 10, 18, 20, 22 and 24 are rejected under 35 U.S.C. §103(a) as being unpatentable over Sota et al. in view of Chiang et al, claims 5, 9, 14, 19 and 23 are rejected under 35 U.S.C. §103(a) as being unpatentable over Sota et al.

Claims 1-26 are now cancelled. New claims 41-57 are presented to clearly define the invention in a patentable way to overcome the rejections under 35 U.S.C. §102(e) and 35 U.S.C. §103(a). Specifically, the new independent claim 41 now includes the limitation that the multi-chip package structure comprises at least two chip packages, each of said chip packages being a packaged chip module. Similarly, the new independent claim 49 includes the limitation that the multi-chip package structure comprises at least a bare chip and at least one chip package, said chip package being a packaged chip module.

The gist of this invention is to provide a multi-chip package structure that integrates at least an already packaged chip module onto the substrate of the multi-chip package structure. By integrating a packaged chip module, the yield of the multi-chip package is greatly increased because the packaged chip module has passed both burned-in and function test.

Sota et al. teaches a semiconductor package structure in which an insulating film

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is applied on the wiring to stretch like a tent, whereby a hollow state at the vent hole can be maintained, thus the function of the vent hole can be well exhibited and any gas or vapor generated from the die-bonding material at the time of reflowing can be reliably released out of the package (col. 6, lines 13-18). As can be seen from the figures of the disclosure, in the semiconductor package structure of Sota et al., **a bare semiconductor chip** is mounted on a chip-mounting region (col. 2, lines 1-21, col. 9, lines 20-30). In contrast to the instant invention, **packaging already packaged chip modules to form a multi-chip package structure has neither been disclosed nor suggested.**

Chiang et al. disclose a semiconductor package comprising a chip which is tested by function test and burn-in test (col. 5, lines 64-67). The semiconductor package structure of Chiang et al. also comprises **a bare semiconductor chip**. **The concept of forming a multi-chip package by packaging already finished chip packages has not been discussed or anticipated.**

None of the cited prior arts has taught or suggested **packaging an already packaged chip module to form a multi-chip package structure.** Therefore, a person having ordinary skill in the art can not reach the subject matter of the invention even if all the cited prior arts are combined.


From the foregoing discussion, it is clear that the instant invention differs from the cited prior arts. The physical difference results in different effects and is not obvious. The new base claims 41 and 49 have overcome all the rejections under 35 U.S.C. §102(e) and 35 U.S.C. §103(a) and should be patentable. By virtue of dependency, claims 41-48 and

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50-57 should also be patentable. Prompt and favorable reconsideration of the application is respectfully solicited.

Respectfully submitted,



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Version with Markings to Show Changes Made

SPECIFICATION:

Page 1, lines 4-8, amend the paragraph as:

The present invention relates to a method of packaging an integrated circuit (IC) package, and particularly, to [multi chip module package (MCM package) of] a low cost and high reliability [to package] method of packaging a plurality of bare [chip] chips and CSP(Chip Scale Package) on a substrate for a multi chip module package (MCM package) so as to increase the package density.

Page 1, lines 11-16, amend the paragraph as:

In conventional semiconductor manufacture, a wafer which is well treated is cut into a plurality of chips, and fixed on a lead frame using gold (Au) wires to connect micro electrodes on the chip and pins of the lead frame. The above structure is then enclosed by suitable [plastic] plastics to protect the internal semiconductor devices. The process to connect the chip to the lead frame and enclose the structure is referred to as packaging.

Page 1, line 17 to page 2, line 4, amend the paragraph as:

The present advanced package, such as CSP (chip scale package), becomes much smaller, lighter, thinner, and shorter compared with the conventional package, such as QFP (Quad Flat [Pack] Package) SOP (Small Outline Package) in order to reduce the cost. Meanwhile, ceramic packaging has been gradually replaced by plastic packaging. The reliability of the product is further enhanced by multi layer interconnect structure, protection layer process, and high quality of packaging. To further reduce the cost of

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[package] packaging is greatly desired in the present IC industry. Therefore, advanced packaging such as CSP or wafer level CSP has been developed to increase the package density. MCM package is one of most promising techniques.

Page 2, lines 5-8, amend the paragraph as:

KGD is defined as [the] a chip that meets the specification and passes the test without wiring. To increase the qualified ratio of a MCM package in the semiconductor process, it is desired to use KGD in packaging. However, the use of KGD [will increase] increases the cost of packaging.

Page 2, lines 11-16, amend the paragraph as:

To overcome the above shortcoming in the conventional IC packaging, an object of the present invention is to provide a method of packaging MCM[package, which] with CSPs as small and thin package bodies and [integrates] integrating those bare [chip] chips and CSP into a ball grid array package (BGA package) to greatly reduce the cost because CSP test has advantages of easy test and low cost compared with conventional KGD test.

Page 2, lines 17-20, amend the paragraph as:

Another object of the present invention is to provide a MCM package structure of low cost and high reliability, which includes a substrate, one or more chip [package] packages, a plurality of electrical connect pins, and a package material to enclose the substrate, the [chip] chips, and the chip package.

Page 4, line 10 to page 5, line 2, amend the paragraph as:

FIGs. 1A and 1B show the structure of a MCM package in the prior arts. The

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package body encloses a plurality of chips, which are interconnected by wire bonding or flip chip bonding. FIG. 1A schematically illustrates the package structure with wire bonding, which comprises a substrate 11, a plurality of chips 12, solder balls 13 under the substrate 11, wires 15 to connect the upper chip 121 and the substrate 11, and package mold resin 14. FIG. 1B schematically illustrates the package structure with flip chip bonding, which comprises a substrate 11, a plurality of chips 12, solder balls 13 under the substrate 11, ball bumps 16 to connect the lower chip 122 and the substrate 11, and package mold resin 14. Since the chips enclosed within the package are not examined by burn-in test and function test (F/T), the yield of the chips are not determined before packaging, and the yield of the package body after packaging can not be promoted. If four chips are enclosed within the package body and each chip has an average F/T yield 99%, the yield of the package is $(99\%) \times (99\%) \times (99\%) \times (99\%) = 96\%$.

Page 5, lines 3-6, amend the paragraph as:

Therefore, the F/T yield of the whole MCM package reduces to 96% after packaging the four chips. The more the chips packaged in the package, the less the yield. It is disadvantageous for the conventional MCM package to [apply to] be used in advanced IC packaging in the future.

Page 5, lines 7-14, amend the paragraph as:

In the prior arts, one solution to [overcome] overcoming the above disadvantage is to provide KGD. To prevent the F/T yield of the package from [reducing] decreasing due to undetermined yield of the [chip] chips, both burn-in test and function test are needed

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for the chips, which will be packaged in subsequent packaging process. Those chips that pass through the above tests are [call] called 'known-good dies', abbreviated as "KGDs". However, the KGD process [is] imposes high cost because the size of the chip is very small and not easily fixed during burn-in test and function test.

Page 5, line 15 to page 6, line 6, amend the paragraph as:

The present invention provides an improved chip packaging method. FIGs. 2A-2D show CSP package structure in the prior arts. CSP is referred to the package that has a size just a little bigger than the chip and has a height less than 1.00 mm. FIG. 2A is a schematic diagram of CSP package structure with wire bonding in the prior arts, FIG. 2B is a schematic diagram of CSP package structure with flip chip bonding in the prior arts, FIG. 2C is a schematic diagram of another CSP package structure with a central pad bonding in the prior arts, and FIG. 2D is a schematic diagram of wafer level CSP in the prior arts. The CSP is not only light, thin, short, and small, but also passes through burn-in test and function test so that the yield of the CSP is not an issue. It is important that the cost of burn-in test and function test of CSP process is much lower than that of the KGD process. Another aspect is that CSP has no yield issue and can easily replace KGD process [to integrate into] for integration into a MCM package because of light, thin, short, and small size.

Page 6, lines 7-11, amend the paragraph as:

Therefore, thin and small CSP or wafer level CSP after testing is served as KGD, which may include bare chips. Those bare chips can connect to the substrate by wire

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bonding or flip chip bonding, and the chips and CSP are further integrated into a ball grid array package (BGA package) so as to achieve the requirement of low cost and high quality for the MCM process.

Page 6, lines 14-20, amend the paragraph as:

FIG. 3A illustrates the first embodiment of MCM package structure in the present invention[, in which the CSP package] which includes CSP packages with wire bonding and flip chip bonding. The CSP is integrated into MCM package process, and includes a substrate 31, solder balls 33 under the substrate 31, package mold resin 34, the CSP body 371 with wire bonding and is electrically connected to the substrate 31, [while] and the CSP 372 with flip chip bonding is electrically connected to the substrate 31.

Page 6, line 23 to page 7, line 5, amend the paragraph as:

FIG. 3B illustrates the second embodiment of MCM package structure in the present invention [, in which the CSP package] which includes CSP packages with flip chip bonding and central pad bonding. The MCM package includes a substrate 31, solder balls 33 under the substrate 31, package mold resin 34, the CSP 372 is electrically connected to the substrate 31, [while] and the CSP 373 is electrically connected to the substrate 31 by the wire 35.

Page 7, lines 8-13, amend the paragraph as:

FIG. 3C illustrates the third embodiment of MCM package structure in the present invention[, in] which includes a bare chip and a CSP package with flip chip bonding. The MCM package includes a substrate 31, solder balls 33 under the substrate 31, package

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mold resin 34, the CSP body 372 is electrically connected to the substrate 31, [while] and the bare chip 321 is electrically connected to the substrate 31 by the wire 35. FIG. 3D is a perspective view of the third embodiment of the MCM package structure in the present invention.

Page 7, lines 16-21, amend the paragraph as:

FIG. 3E illustrates the fourth embodiment of MCM package structure in the present invention[, in] which includes a bare chip and a [the] CSP package with wire bonding. The MCM package includes a substrate 31, solder balls 33 under the substrate 31, package mold resin 34, the[.] CSP body 371 is electrically connected to the substrate 31, [while] and the bare chip 322 is electrically connected to the substrate 31 by means of flip-chip bonding.

Page 8, lines 1-7, amend the paragraph as:

FIG. 3F illustrates the fifth embodiment of MCM package structure in the present invention[, in] which includes a bare chip and a [the] CSP 373 package with a central pad bonding. The MCM package includes a substrate 31, solder balls 33 under the substrate 31, package mold resin 34, the[.] CSP 373 with a central pad bonding is electrically connected to the substrate 31 by the wires 35, [while] and the bare chip 321 is electrically connected to the substrate 31 by the wires 35.